

**SEMITOP® 3**

**3-phase bridge rectifier +  
brake chopper +3-phase  
bridge inverter**  
**SK 8 DGD L 065 ET**

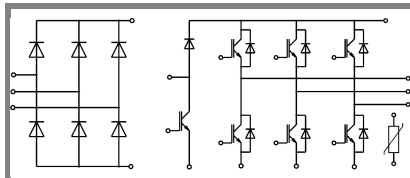
Target Data

## Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DCB)
- Ultrafast NPT technology IGBT
- CAL Technology FWD
- Integrated NTC temperature sensor

## Typical Applications\*

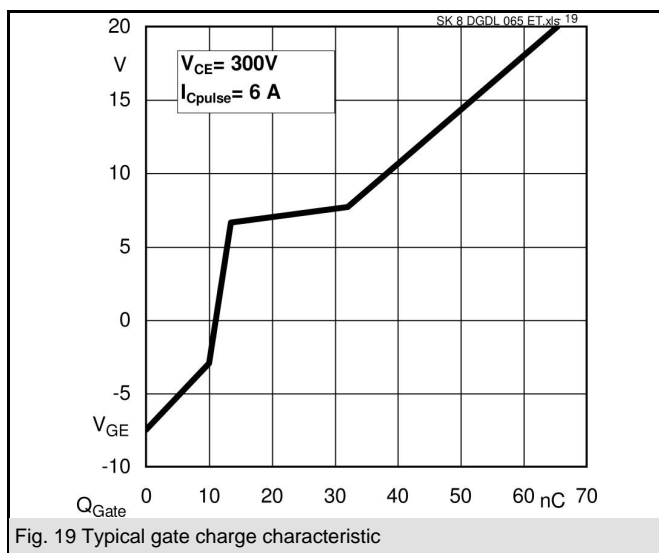
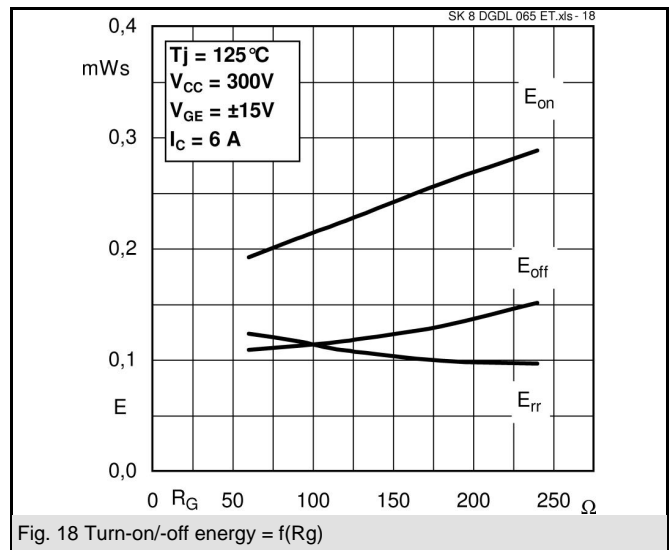
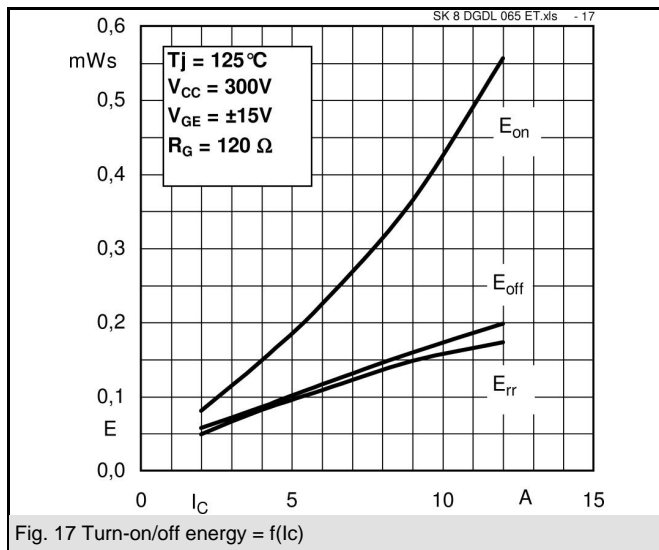
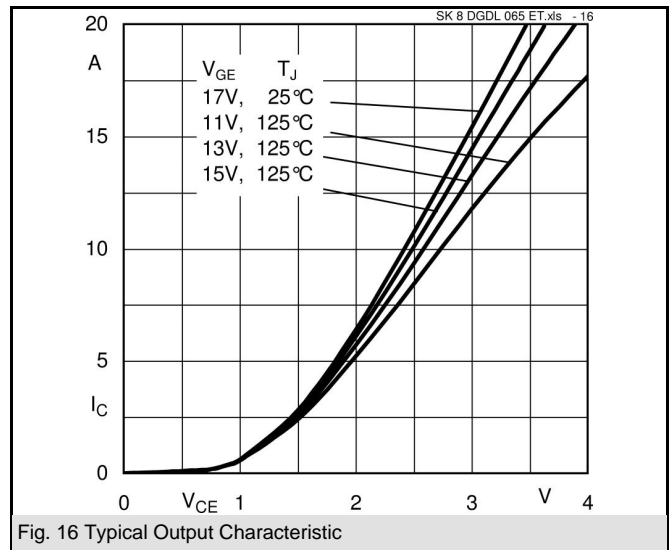
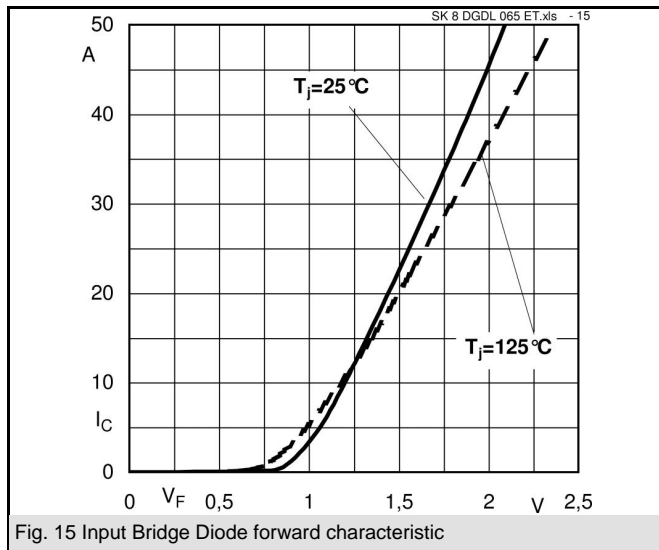
- Inverter
- Servo drives



**DGD L - ET**

Absolute Maximum Ratings		$T_s = 25^\circ\text{C}$ , unless otherwise specified	
Symbol	Conditions	Values	Units
<b>IGBT - Inverter, Chopper</b>			
$V_{CES}$	$T_s = 25 (80)^\circ\text{C}$	600	V
$I_C$	$I_{CRM} = 2 \times I_{Cnom}$ , $t_p = 1 \text{ ms}$	12 (8)	A
$I_{CRM}$		12	A
$V_{GES}$		$\pm 20$	V
$T_j$		-40 ... +150	$^\circ\text{C}$
<b>Diode - Inverter, Chopper</b>			
$I_F$	$T_s = 25 (80)^\circ\text{C}$	(13)	A
$I_{FRM}$	$I_{FRM} = 2 \times I_{Fnom}$ , $t_p = 1 \text{ ms}$	16	A
$T_j$		-40 ... +150	$^\circ\text{C}$
<b>Rectifier</b>			
$V_{RRM}$	$T_s = 80^\circ\text{C}$	1600	V
$I_D$	$t_p = 10 \text{ ms}$ , $\sin 180^\circ$ , $T_j = 25^\circ\text{C}$	33	A
$I_{FSM} / I_{TSM}$	$t_p = 10 \text{ ms}$ , $\sin 180^\circ$ , $T_j = 25^\circ\text{C}$		A
$I_t^2$	$t_p = 10 \text{ ms}$ , $\sin 180^\circ$ , $T_j = 25^\circ\text{C}$		$\text{A}^2\text{s}$
$T_j$		-40 ... +150	$^\circ\text{C}$
$T_{sol}$	Terminals, 10s	260	$^\circ\text{C}$
$T_{stg}$		-40 ... +125	$^\circ\text{C}$
$V_{isol}$	AC, 1 min. / 1s	2500 / 3000	V

Characteristics		$T_s = 25^\circ\text{C}$ , unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
<b>IGBT - Inverter, Chopper</b>					
$V_{CEsat}$	$I_C = 6 \text{ A}$ , $T_j = 25 (125)^\circ\text{C}$		2 (2,2)		V
$V_{GE(th)}$	$V_{GE} = V_{CE}$ , $I_C = 0,5 \text{ mA}$	3	4	5	V
$V_{CE(TO)}$	$T_j = 25^\circ\text{C}$ (125) $^\circ\text{C}$		1,2 (1,1)		V
$r_T$	$T_j = 25^\circ\text{C}$ (125) $^\circ\text{C}$		133 (183)		m $\Omega$
$C_{ies}$	$V_{CE} = 25 \text{ V}$ , $V_{GE} = 0 \text{ V}$ , $f = 1 \text{ MHz}$		0,35		nF
$C_{oes}$	$V_{CE} = 25 \text{ V}$ , $V_{GE} = 0 \text{ V}$ , $f = 1 \text{ MHz}$		0,04		nF
$C_{res}$	$V_{CE} = 25 \text{ V}$ , $V_{GE} = 0 \text{ V}$ , $f = 1 \text{ MHz}$		0,03		nF
$R_{th(j-s)}$	per IGBT			2,6	K/W
$t_{d(on)}$	under following conditions		20		ns
$t_r$	$V_{CC} = 300 \text{ V}$ , $V_{GE} = \pm 15 \text{ V}$		25		ns
$t_{d(off)}$	$I_C = 6 \text{ A}$ , $T_j = 125^\circ\text{C}$		145		ns
$t_f$	$R_{Gon} = R_{Goff} = 120 \Omega$		25		ns
$E_{on}$	inductive load		0,22		mJ
$E_{off}$			0,12		mJ
<b>Diode - Inverter, Chopper</b>					
$V_F = V_{EC}$	$I_F = 8 \text{ A}$ , $T_j = 25 (125)^\circ\text{C}$		1,35		V
$V_{(TO)}$	$T_j = 25^\circ\text{C}$ (125) $^\circ\text{C}$		(0,8)	(0,9)	V
$r_T$	$T_j = 25^\circ\text{C}$ (125) $^\circ\text{C}$		(44)		m $\Omega$
$R_{th(j-s)}$	per diode			2,7	K/W
$I_{RRM}$	under following conditions		4,2		A
$Q_{rr}$	$I_F = 8 \text{ A}$ , $V_R = 300 \text{ V}$		0,65		$\mu\text{C}$
$E_{rr}$	$V_{GE} = 0 \text{ V}$ , $T_j = 125^\circ\text{C}$				mJ
	$di_F/dt = -120 \text{ A}/\mu\text{s}$				
<b>Diode rectifier</b>					
$V_F$	$I_F = 20 \text{ A}$ , $T_j = 25 (125)^\circ\text{C}$		1,45		V
$V_{(TO)}$	$T_j = 125^\circ\text{C}$		0,82		V
$r_T$	$T_j = 125^\circ\text{C}$		35		m $\Omega$
$R_{th(j-s)}$	per diode			2,8	K/W
<b>Temperature sensor</b>					
$R_{ts}$	5 %, $T_r = 25 (100)^\circ\text{C}$		5000(493)		$\Omega$
<b>Mechanical data</b>					
w			30		g
$M_s$	Mounting torque	2,25		2,5	Nm



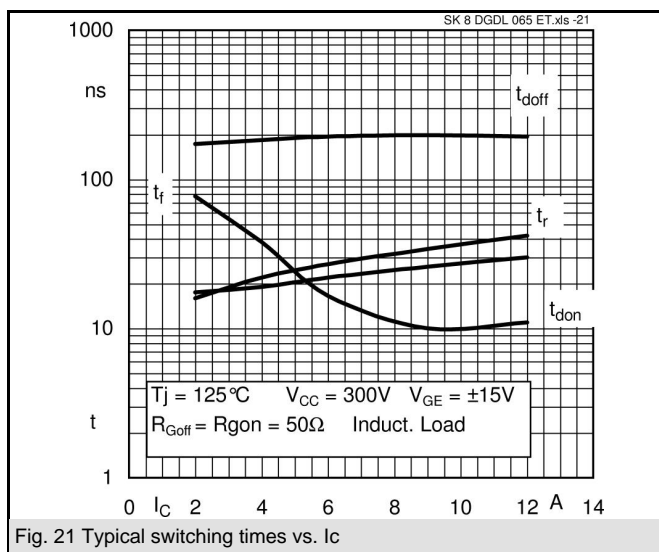


Fig. 21 Typical switching times vs.  $I_C$

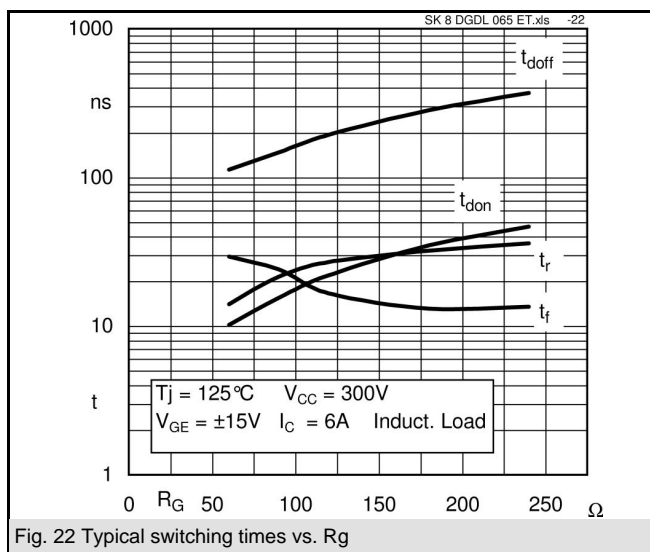


Fig. 22 Typical switching times vs.  $R_G$

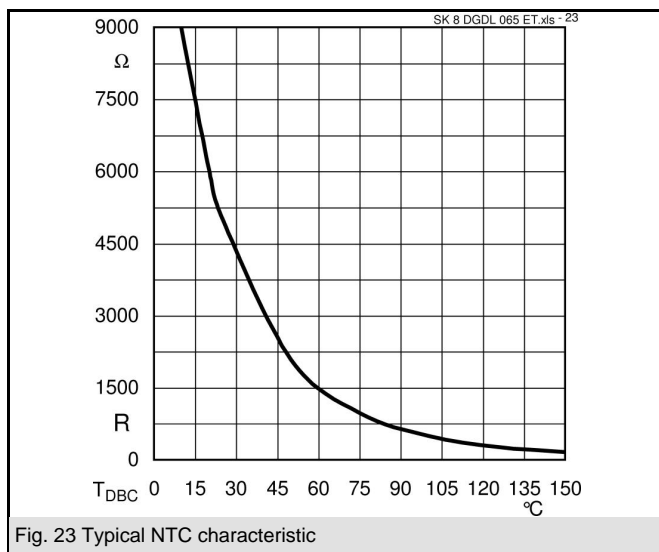


Fig. 23 Typical NTC characteristic

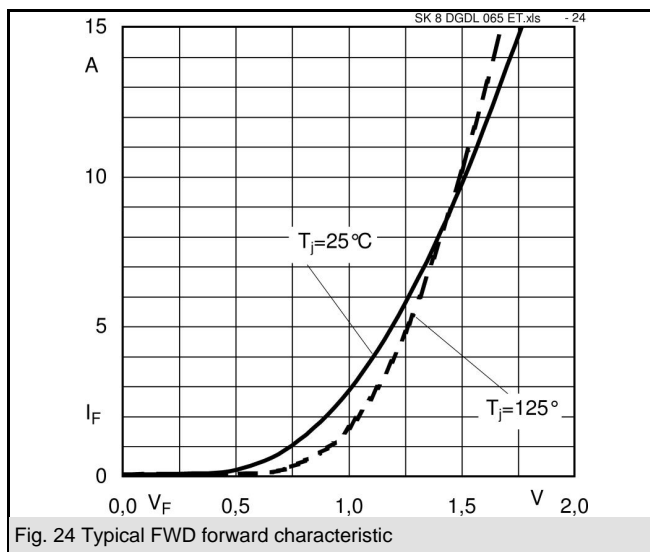
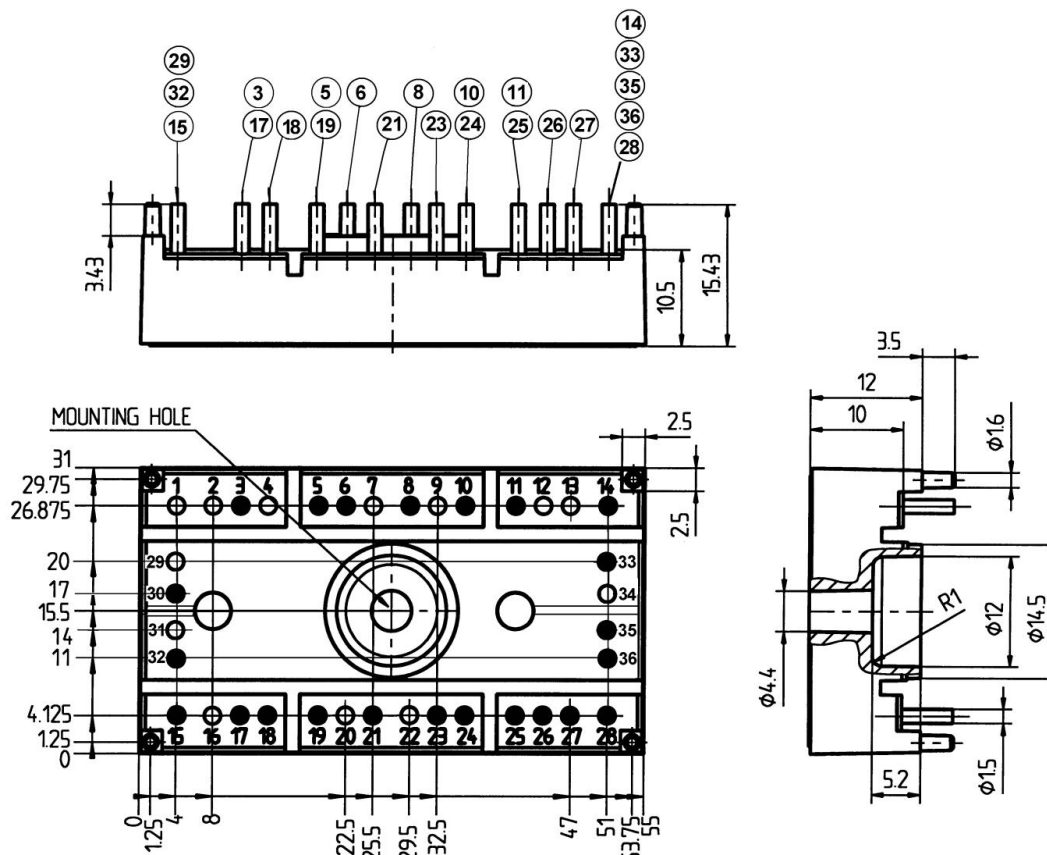
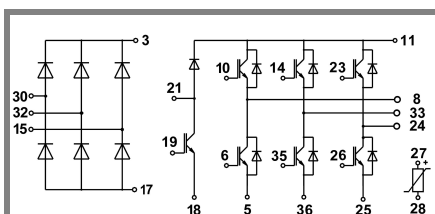


Fig. 24 Typical FWD forward characteristic



Case T 49 (Suggested hole diameter, in the PCB, for solder pins and plastic mounting pins: 2mm)



Case T 49

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

\* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.